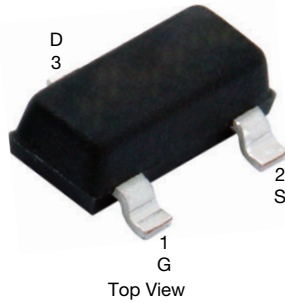


Automotive N-Channel 60 V (D-S) 175 °C MOSFET

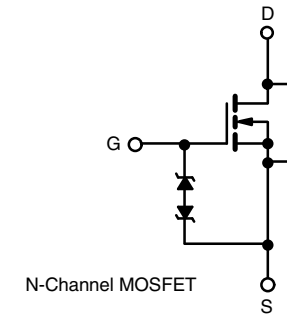
SOT-23 (TO-236)



FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rg and UIS tested
- Typical ESD protection 800 V
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912

 AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE


PRODUCT SUMMARY	
V_{DS} (V)	60
$R_{DS(on)}$ (Ω) at $V_{GS} = 1.5$ V	0.245
I_D (A)	4
Configuration	Single
Package	SOT-23

Marking code: 9Jxxx

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	60	V
Gate-source voltage		V_{GS}	± 8	
Continuous drain current	$T_C = 25$ °C	I_D	2	A
	$T_C = 125$ °C		1.3	
Continuous source current (diode conduction)		I_S	2	
Pulsed drain current ^a		I_{DM}	8	
Single pulse avalanche current	L = 0.1 mH	I_{AS}	5	
Single pulse avalanche energy		E_{AS}	1.25	
Maximum power dissipation ^a	$T_C = 25$ °C	P_D	3	W
	$T_C = 125$ °C		1	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount ^b	R_{thJA}	166	°C/W
Junction-to-foot (drain)		R_{thJF}	50	

Notes

- Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)



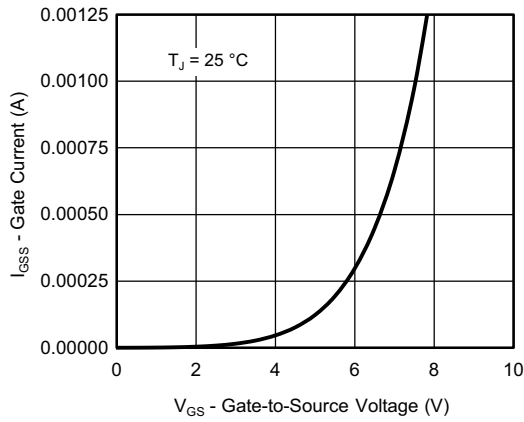
SPECIFICATIONS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$		60	-	-	V
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		0.46	0.6	1	
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 3\text{ V}$		-	-	± 100	nA
		$V_{DS} = 0\text{ V}, V_{GS} = \pm 8\text{ V}$		-	-	± 5.5	
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	150	
On-state drain current ^a	$I_{D(on)}$	$V_{GS} = 4.5\text{ V}$	$V_{DS} \geq 5\text{ V}$	2	-	-	A
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}$	$I_D = 2\text{ A}, T_J = 25\text{ }^\circ\text{C}$	-	0.190	0.240	Ω
		$V_{GS} = 4.5\text{ V}$	$I_D = 2\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.460	
		$V_{GS} = 4.5\text{ V}$	$I_D = 2\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.600	
		$V_{GS} = 1.5\text{ V}$	$I_D = 2\text{ A}$	-	0.195	0.245	
Forward transconductance ^b	g_{fs}	$V_{DS} = -15\text{ V}, I_D = 1\text{ A}$		-	8.8	-	S
Dynamic ^b							
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	-	263	330	μF
Output capacitance	C_{oss}			-	28	35	
Reverse transfer capacitance	C_{rss}			-	15	19	
Total gate charge ^c	Q_g	$V_{GS} = 4.5\text{ V}$	$V_{DS} = 30\text{ V}, I_D = 1.5\text{ A}$	-	2	2.5	nC
Gate-source charge ^c	Q_{gs}			-	0.3	-	
Gate-drain charge ^c	Q_{gd}			-	0.6	-	
Gate resistance	R_g	f = 1 MHz		2.5	4.1	6.6	Ω
Turn-on delay time ^c	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong 1.5\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		-	6	7.2	ns
Rise time ^c	t_r			-	11	14	
Turn-off delay time ^c	$t_{d(off)}$			-	26	32	
Fall time ^c	t_f			-	13	16	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed current ^a	I_{SM}			-	-	8	A
Forward voltage	V_{SD}	$I_F = 2\text{ A}, V_{GS} = 0$		-	0.8	1.2	V

Notes

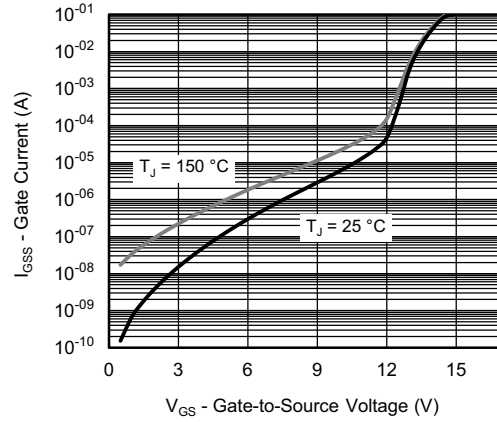
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

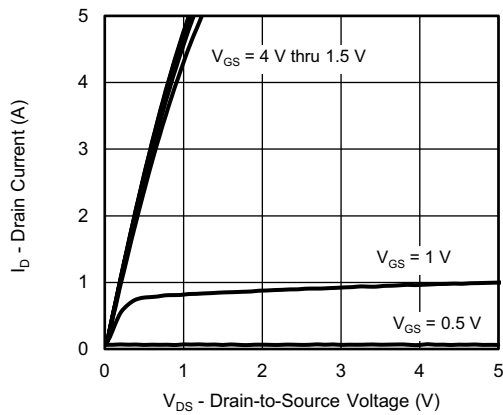
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



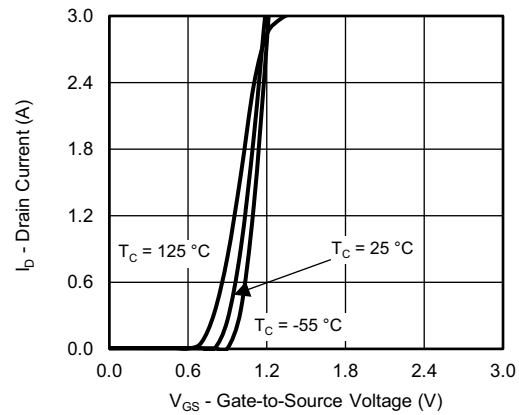
Gate Current vs. Gate-Source Voltage



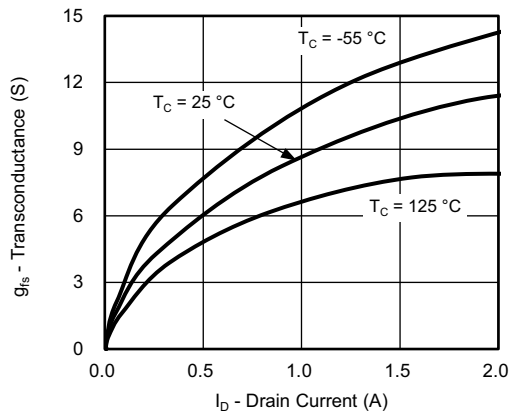
Gate Current vs. Gate-Source Voltage



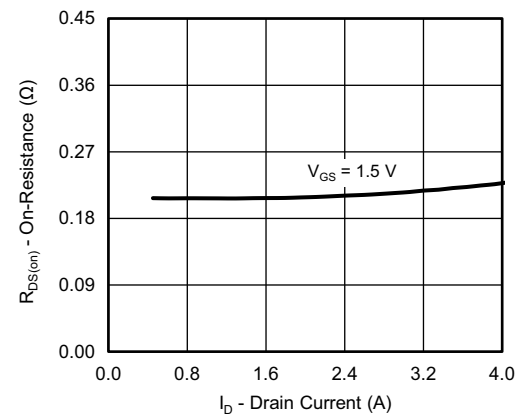
Output Characteristics



Transfer Characteristics



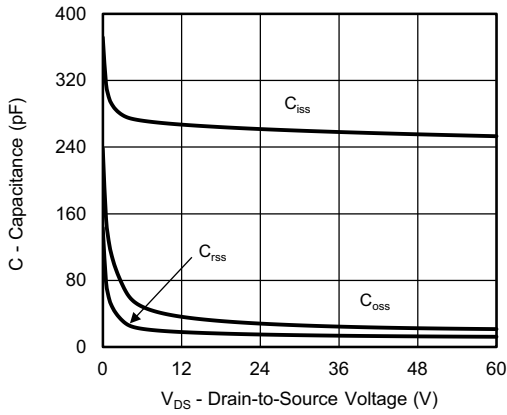
Transconductance



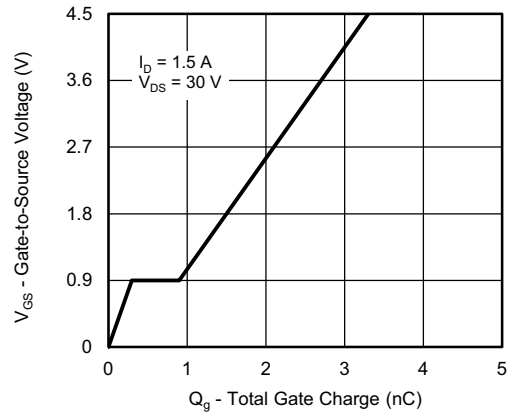
On-Resistance vs. Drain Current



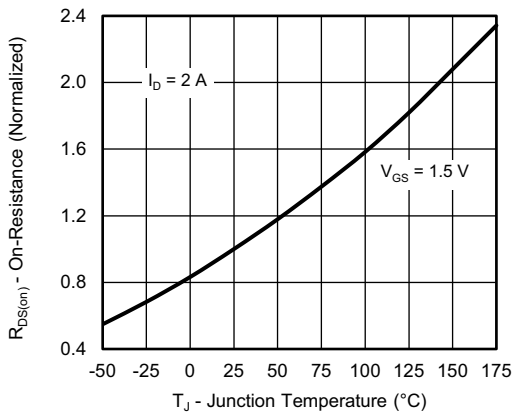
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



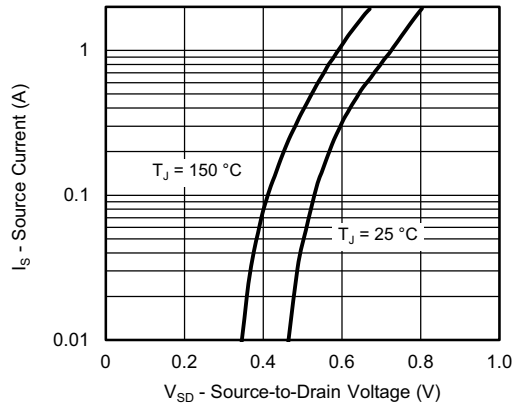
Capacitance



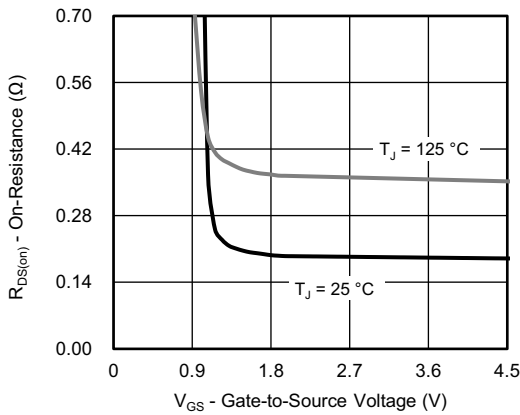
Gate Charge



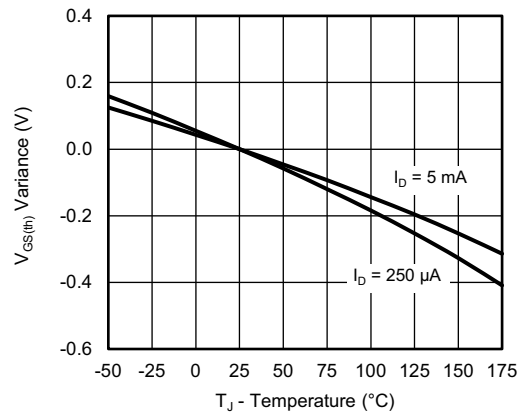
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

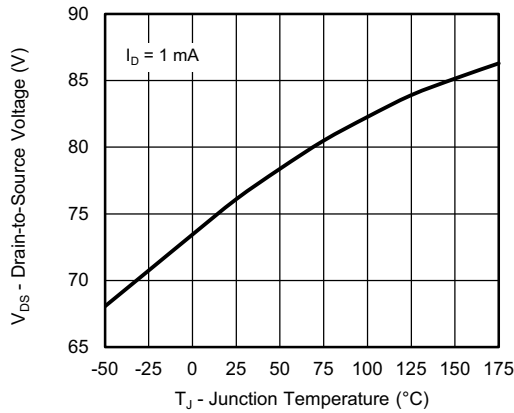


On-Resistance vs. Gate-Source Voltage

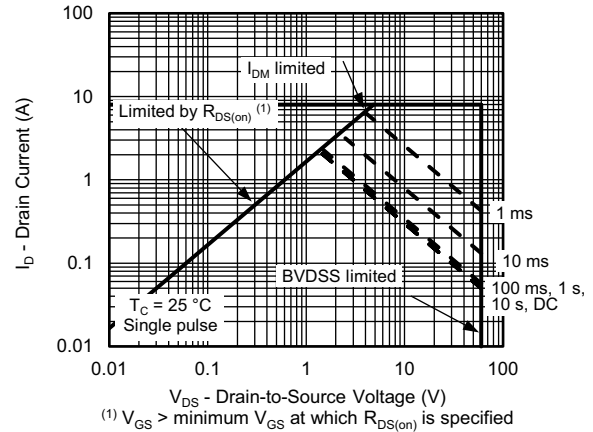


Threshold Voltage

TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



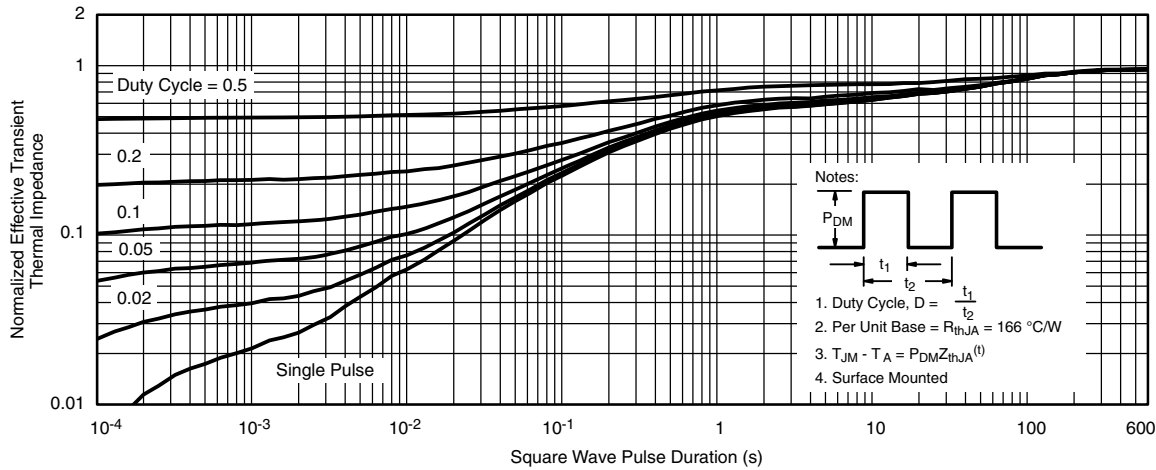
Drain-Source Breakdown vs. Junction Temperature



⁽¹⁾ $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)

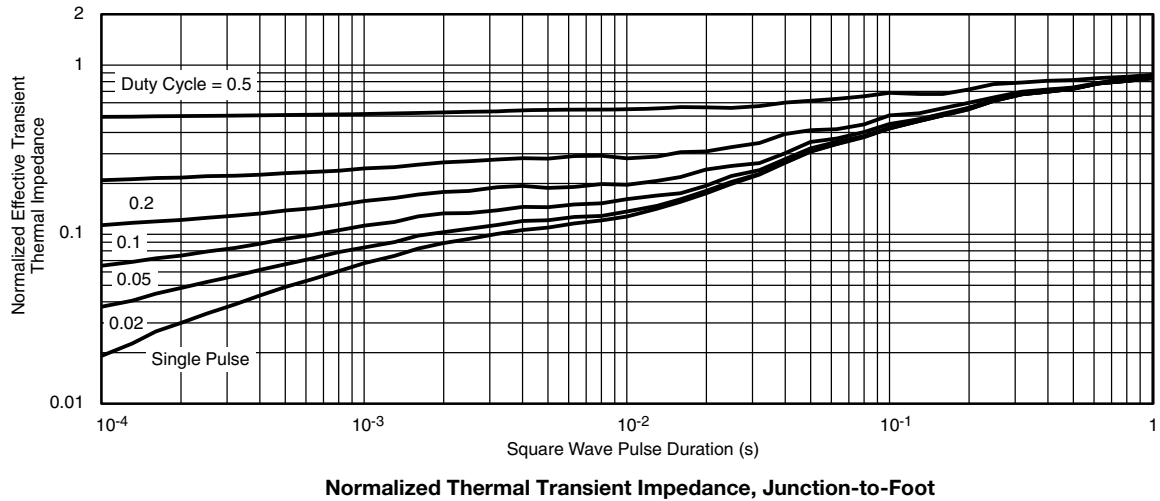


- Notes:
- Duty Cycle, $D = \frac{t_1}{t_2}$
 - Per Unit Base = $R_{thJA} = 166\text{ }^\circ\text{C/W}$
 - $T_{JM} - T_A = P_{DM}Z_{thJA}^{(1)}$
 - Surface Mounted

Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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